

ANALYSIS OF SILICON STRESS/STRAIN RELATIONSHIPS

UNIVERSITY OF KENTUCKY

O. Dillon

$$\dot{\epsilon}_{ij} = \frac{(1+\nu)}{E} \dot{\sigma}_{ij} - \frac{\nu \dot{\sigma}_{kk} \delta_{ij}}{E} + \dot{\epsilon}_{ij}^{PL} \quad (1)$$

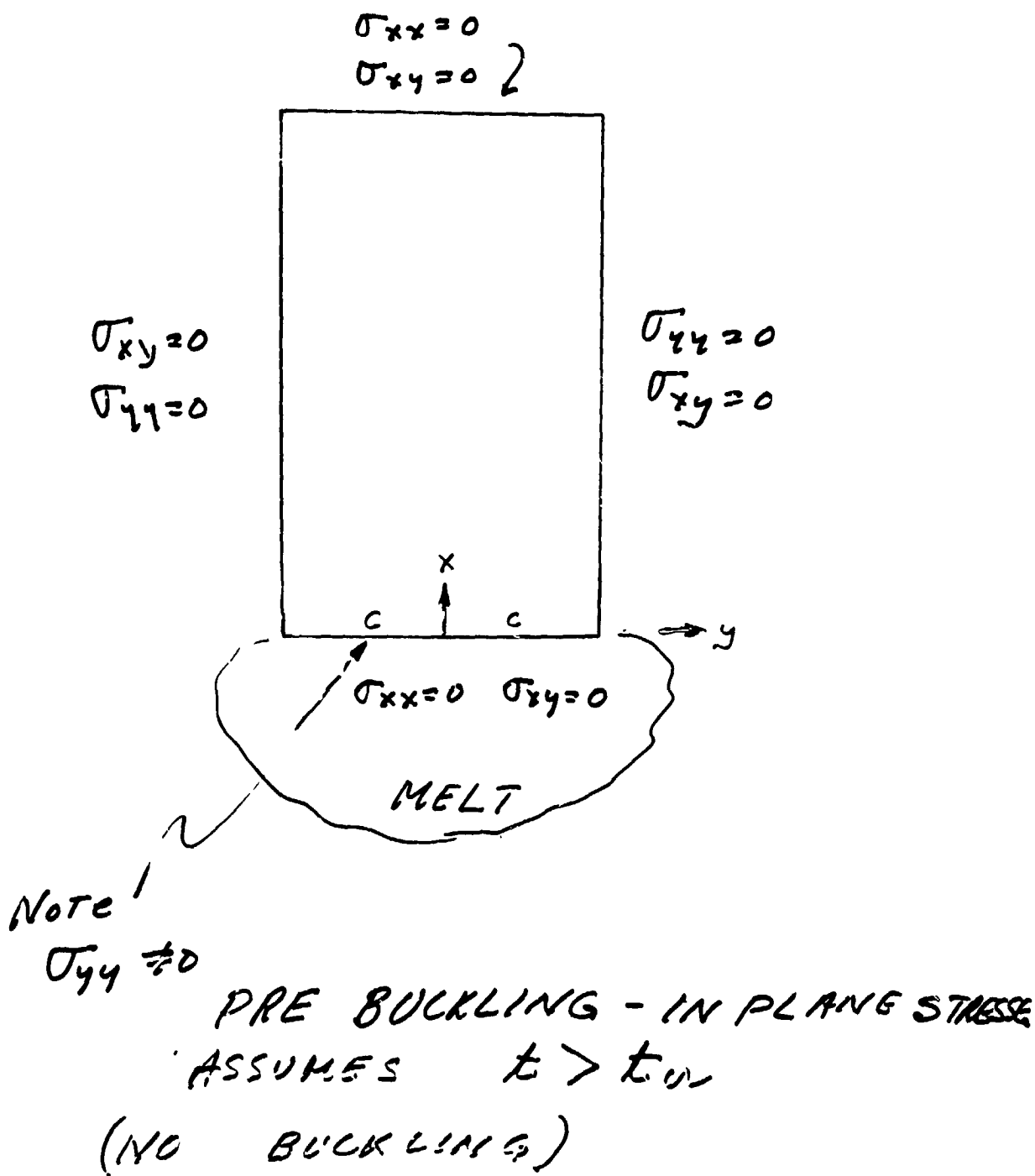
where the inelastic strain rate tensor $\dot{\epsilon}_{ij}^{PL}$ is the plastic strain rate and is

$$\dot{\epsilon}_{ij}^{PL} = f S_{ij} \quad (2)$$

where S_{ij} are the deviatoric stress components and where

$$f = \frac{bB}{\tau_0 m} N_m (\sqrt{J_2} - D\sqrt{N_m}) \frac{e^{-Q/kT}}{\sqrt{J_2}} \quad (3)$$

ADVANCED SILICON SHEET



$$\nabla^2(\sigma_{xx} + \sigma_{yy}) = -\alpha E \nabla^2 T + \frac{1}{\nu} \int_0^x \left(\frac{\partial^2 \dot{\epsilon}_{xx}^{PL}}{\partial y^2} + \frac{\partial^2 \dot{\epsilon}_{yy}^{PL}}{\partial x^2} - 2 \frac{\partial^2 \dot{\epsilon}_{xy}^{PL}}{\partial x \partial y} \right) E \, du \quad (8)$$

$$\sigma_{xx} = \frac{2}{f} \left[\dot{\epsilon}_{xx}^{oc} + \frac{1}{2} \dot{\epsilon}_{yy}^{oc} - z \frac{\partial^2 w^c}{\partial x^2} - \frac{z}{2} \frac{\partial^2 w^c}{\partial y^2} \right]$$

where w^c is the creep (viscoplastic) portion of the transverse displacement.

The moment intensity is related to the stress by the basic definition.

$$M_{xx} = - \int_{-h/2}^{h/2} \sigma_{xx} z \, dz$$

The "elastic moment" M_{xx}^e is then

$$M_{xx}^e = \frac{E h^3}{12(1-\nu^2)} \left[\frac{\partial^2 w^e}{\partial x^2} + \nu \frac{\partial^2 w^e}{\partial y^2} \right] \quad (5)$$

while the corresponding "inelastic" moment component is

$$M_{xx}^c = \frac{1}{f} \left[\frac{\partial^2 w^c}{\partial x^2} + \frac{1}{2} \frac{\partial^2 w^c}{\partial y^2} \right] \frac{h^3}{12} \quad (6)$$

Since the moments are the same, the displacements are clearly related by

$$\frac{\partial^2 w^c}{\partial x^2} = \frac{f E}{(1-\nu^2)} \frac{\partial^2 w^e}{\partial x^2} \quad (7)$$

$$D \nabla^4 w^e = N_{xx} \frac{\partial^2 w^e}{\partial x^2} + 2N_{xy} \frac{\partial^2 w^e}{\partial x \partial y} + N_{yy} \frac{\partial^2 w^e}{\partial y^2}$$

$$+ \frac{f E h^3}{12(1-\nu^2)} \left[N_{xx} \frac{\partial^2 w^e}{\partial x^2} + 2N_{xy} \frac{\partial^2 w^e}{\partial x \partial y} + N_{yy} \frac{\partial^2 w^e}{\partial y^2} \right] \quad (9)$$

ADVANCED SILICON SHEET

$$w^e(x,y,t) = g(t)W(x,y) \quad (10)$$

and obtain

$$\ddot{g} - \lambda^2 g = 0 \quad (11)$$

for the time part and

$$D \nabla^4 W = N_{\alpha\beta}^0 \left(1 + \frac{f F}{12(1-\nu^2)\lambda^2} \right) \frac{\partial^2 W}{\partial x_\alpha \partial x_\beta} \quad (12)$$

Hence one can see that the inelastic material behavior results in buckling very much like the elastic case but with the pseudo in plane forces given by

$$N_{\alpha\beta}^0 \left(1 + \frac{f E}{12(1+\nu^2)} \frac{1}{\lambda^2} \right) \quad (13)$$

The separation parameter λ^2 in Eq (13) reflects how "fast" the lateral deflections grow from some initial value. Clearly the presence of $f(x,y)$ in the numerator of Eq (13) makes similar interpretation impossible for λ^2 except as given in Eq (11).

To obtain values for λ^2 , we use a Galerkin method on Eq (12) and find that

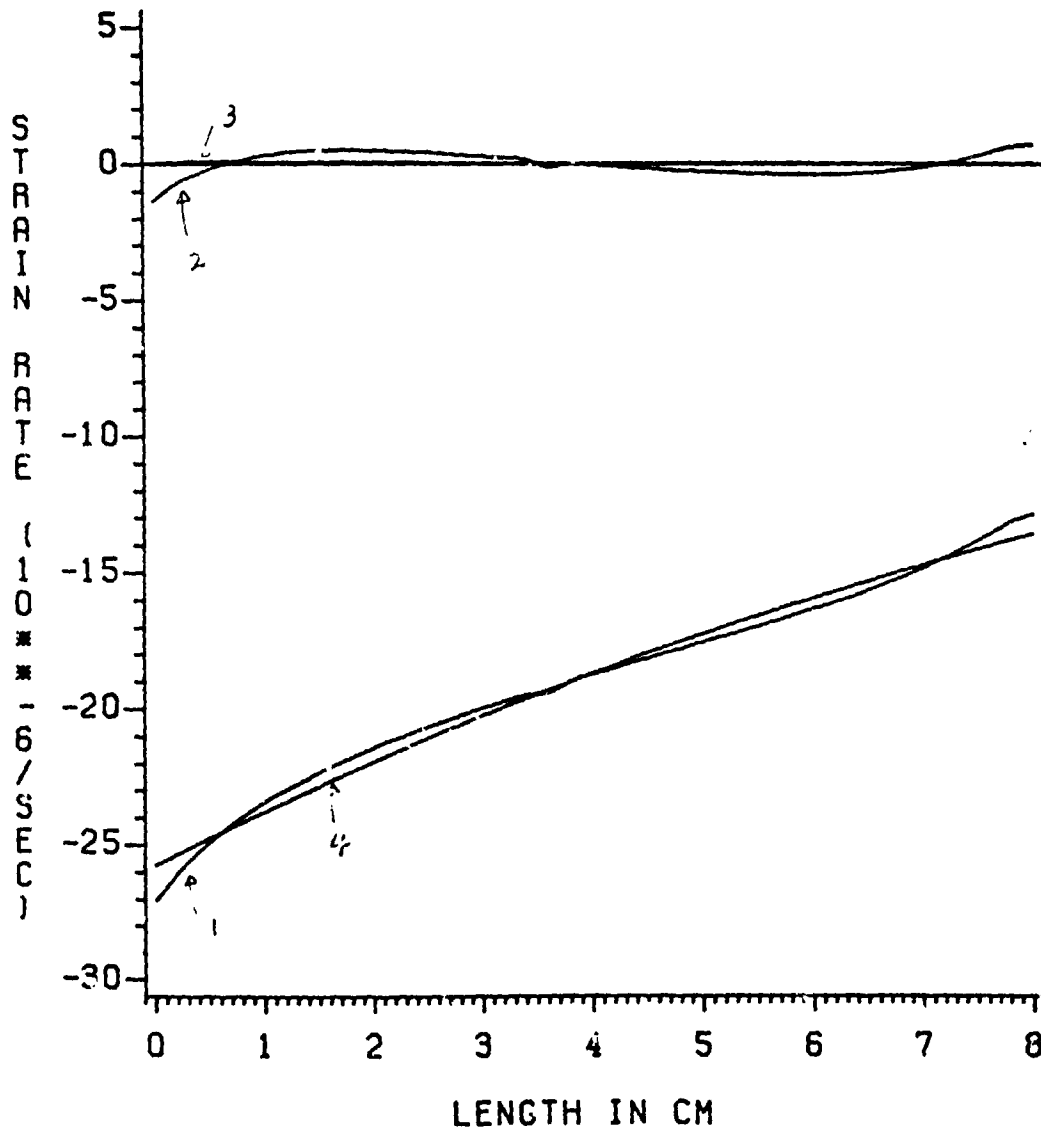
$$\lambda^2 = \frac{2 h^3}{3(h^3 - h_{cr}^3)} \frac{\iint f E^2 \nabla^4 W W \, da}{\iint E \nabla^4 W W \, da} \quad (14)$$



ADVANCED SILICON SHEET

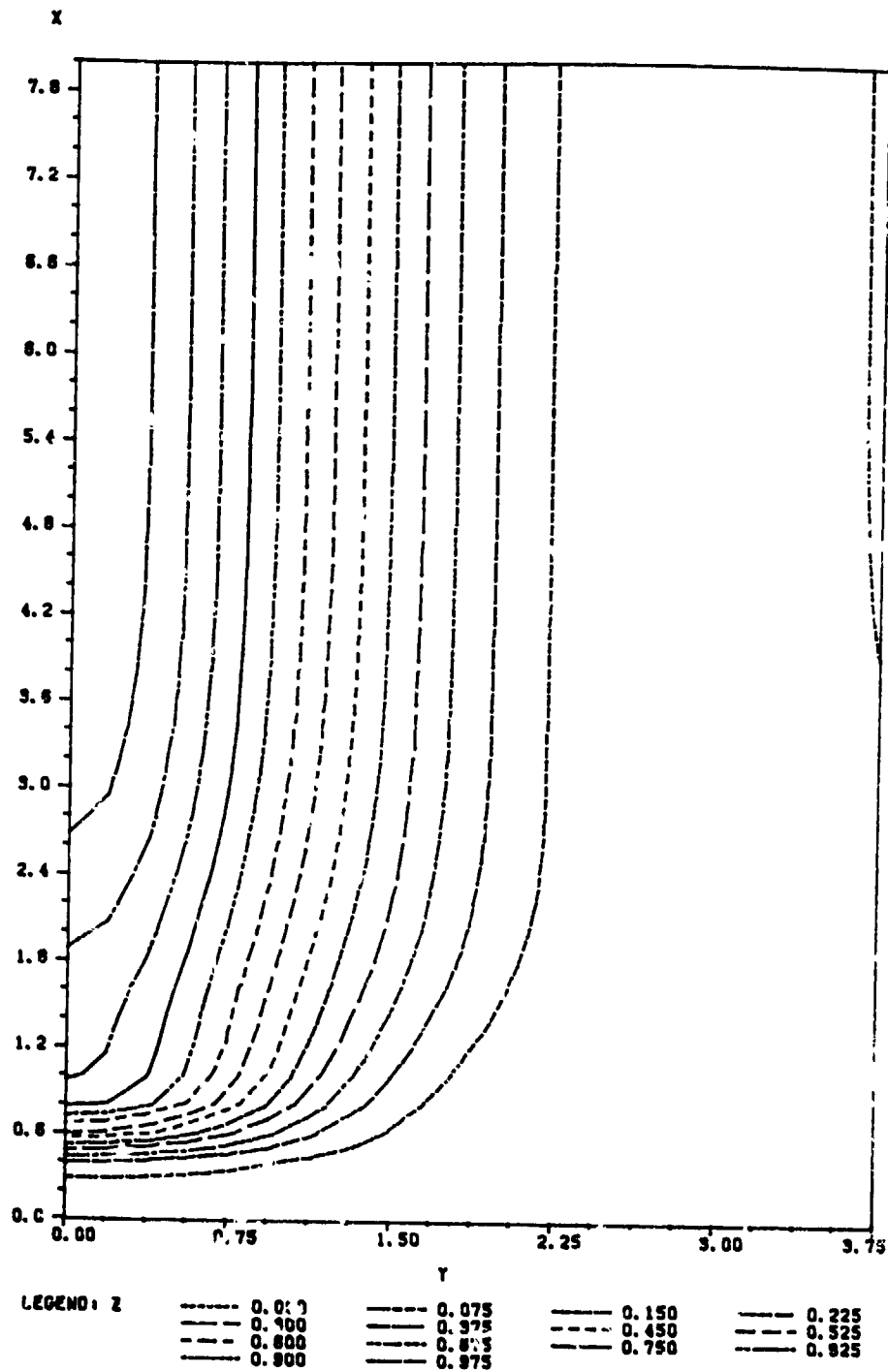
Normal Strain Rate XX Along Y = 0 (Centerline)
for $T = 1440 \cdot \text{Exp}(-0.08X)$ Width = 6.0 CM

LINE 1 IS TOTAL, LINE 2 IS ELASTIC, LINE 3
IS PLASTIC AND LINE 4 IS THERMAL STRAIN RATE



ADVANCED SILICON SHEET

The Dislocation Density Contour Plot
 for $T = 1440 \cdot \text{Exp}(-0.08X)$
 Unit of X and Y = CM, Unit of Z = 10^3 Per CM^2



ADVANCED SILICON SHEET

$$6.0 \text{ cm} \times 6.0 \text{ cm}$$

$$T = T_{cr}$$

The results are

N_i /cm ²	N_f max /cm ²	σ_{yy} max MPa	σ_{xx} max MPa	t_{2cr} mm	t_{2cr} m
3	2497	-22.64	15.23	.1936(c)	.1375(t)
.15	1092	-22.65	15.99	.1965(c)	.1388(t)
.01	266	-23.69	17.1	.1982(c)	.1394(t)

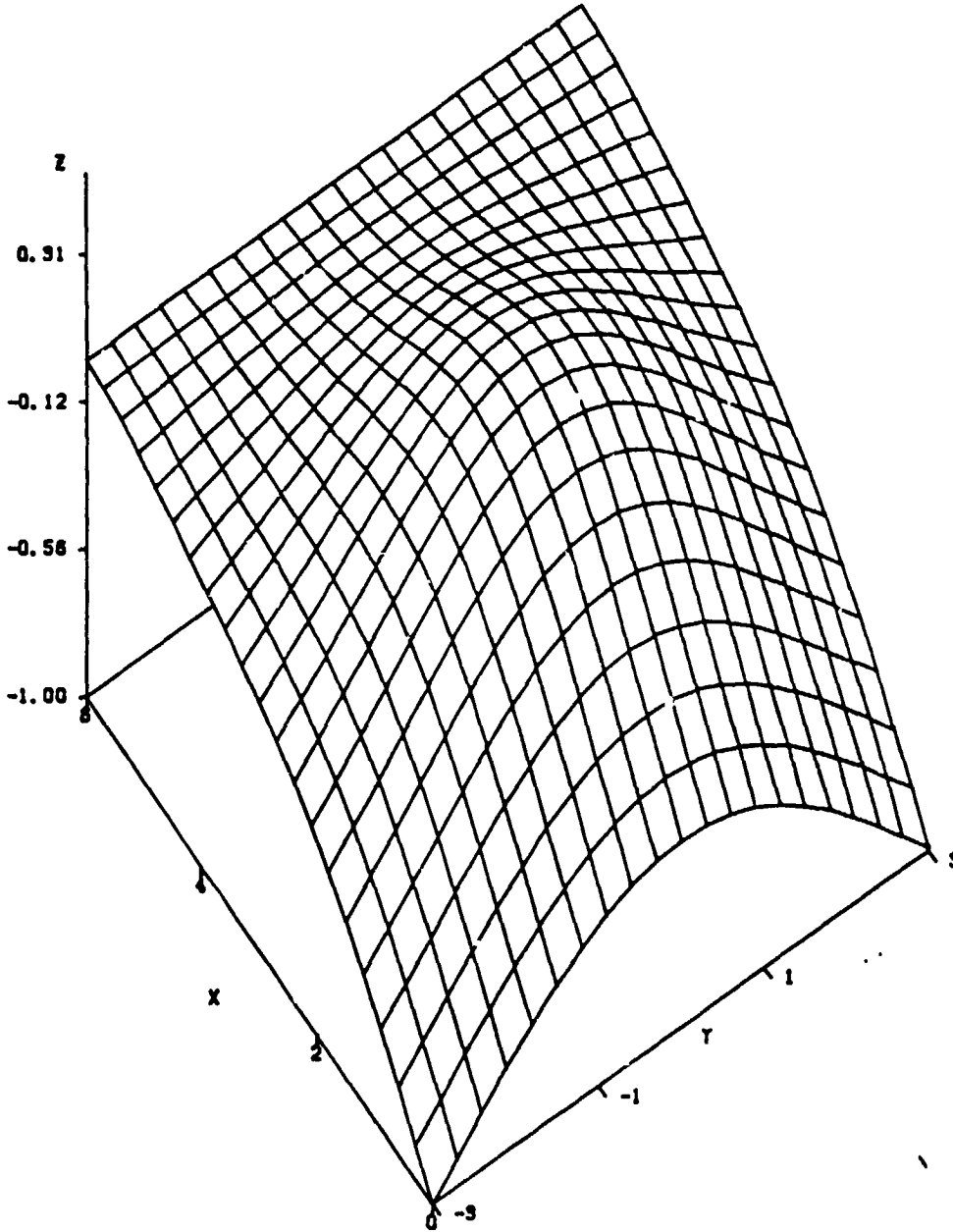
	D→100	Larger backstress			
.3	1811	-22.64	15.41	.1948(c)	.1381(t)

Table I

C-7

ADVANCED SILICON SHEET

The 20th Elastic Buckling Mode
for Westinghouse Temperature Profile
Critical Thickness = 0, 19817 MM
Unit of X and Y = CM



ADVANCED SILICON SHEET

Mode	hcr (mm)	λ^2 (sec ⁻¹)	
1	.1936	+.06668	critical case
2	.1375	+.01124	
3	.1132	+.00742	
4	.1031	+.00452	
5	.0893	+.00365	
6	.08503	+.00153	
7	.07565	+.00698	
8	.06755	+.00117	
9	.06644	+.006555	
10	.04985	-.0000416	
11	.04086	+.0000832	

$T = T_w$

$No = .3/cm^2$

6cm x 6cm

ADVANCED SILICON SHEET

Mode	hcr (mm)	λ^2 (sec ⁻¹)	
1	.1965	+.02937	critical case
2	.1388	+.004919	
3	.1099	+.003094	
4	.1074	+.0018414	
5	.09146	+.0016733	
6	.08562	+.000734	
7	.076924	+.001504	
8	.069803	+.000597	
9	.06800	+.000367	
10	.062011	+.006800	

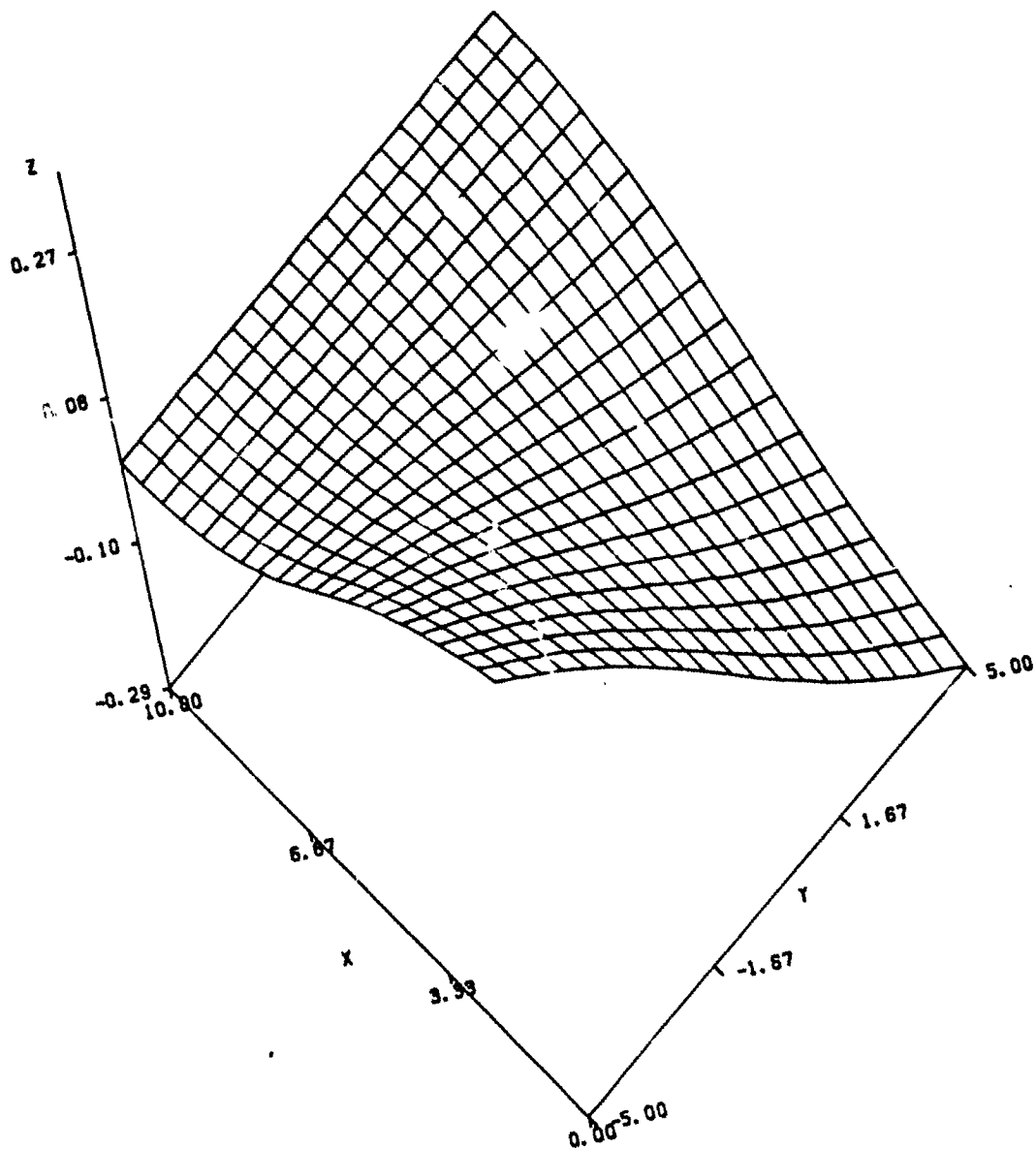
$$T = T_w$$

$$N_0 = .15/\text{cm}^2$$

6cm x 6cm

ADVANCED SILICON SHEET

The First Positive Buckling Mode
for Westinghouse Temperature Profile
Critical Thickness = 0.76154 MM
Unit of X and Y = CM



ADVANCED SILICON SHEET

Mode	hcr (mm)	$\lambda^2 \text{sec}^{-1}$	
1	.4204	-1.706×10^{-3}	
2	.3872	-7.164×10^{-3}	
3	.3346	-5.623×10^{-4}	
4	.3080	$+2.8909 \times 10^{-3}$	
5	.2789	$+4.9641 \times 10^{-3}$	critical case
6	.2663	-7.8054×10^{-4}	
7	.2337	$+2.3418 \times 10^{-4}$	
8	.2281	-1.1527×10^{-3}	
9	.2044	-6.0790×10^{-4}	
10	.1974	$+1.2900 \times 10^{-4}$	
11	.1801	-2.0870×10^{-4}	
12	.1724	$+1.0930 \times 10^{-4}$	

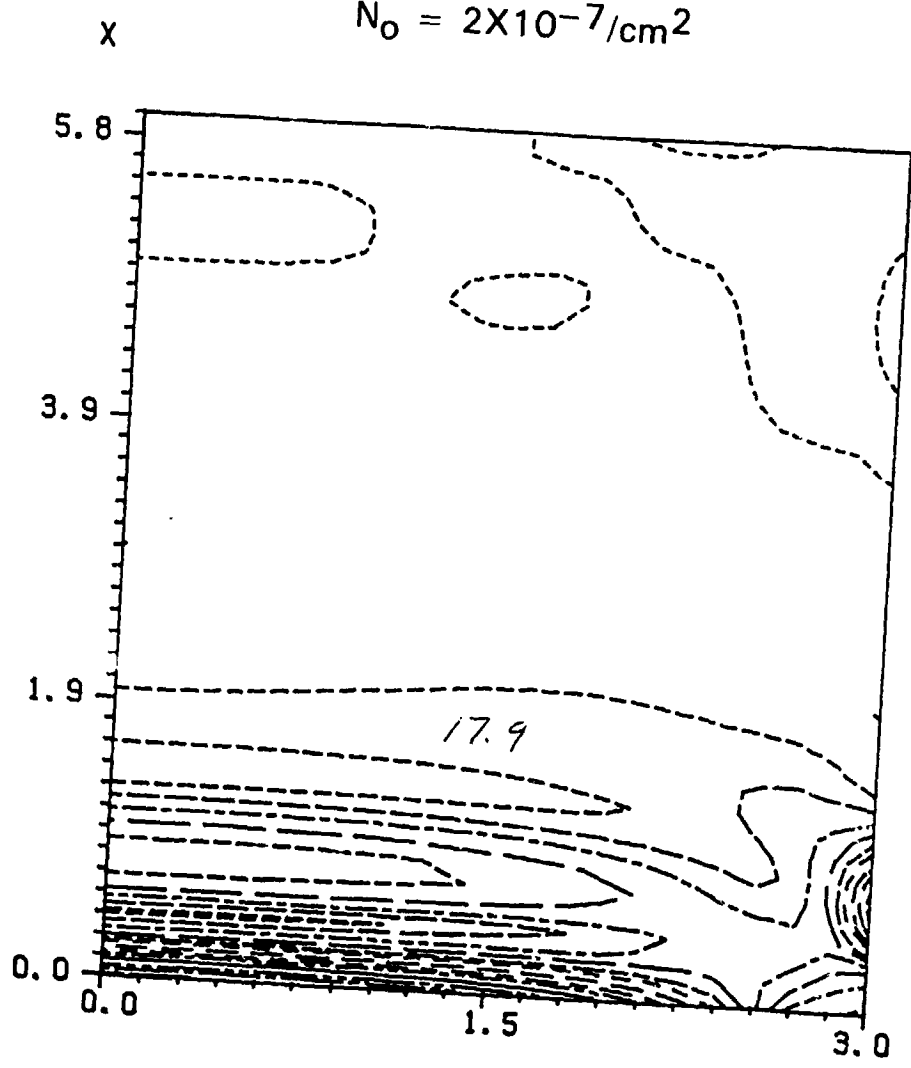
T = Modified EFG
 $N_0 = 2 \times 10^{-7} / \text{cm}^2$
 6cm x 6 cm

Run V-0545
 8 June

ADVANCED SILICON SHEET

The Effectiveness Stress Contour Plot
 for Modified EFG Profile
 Unit of X and Y = CM, Z = MPA

$$N_0 = 2 \times 10^{-7} / \text{cm}^2$$



LEGEND: Z

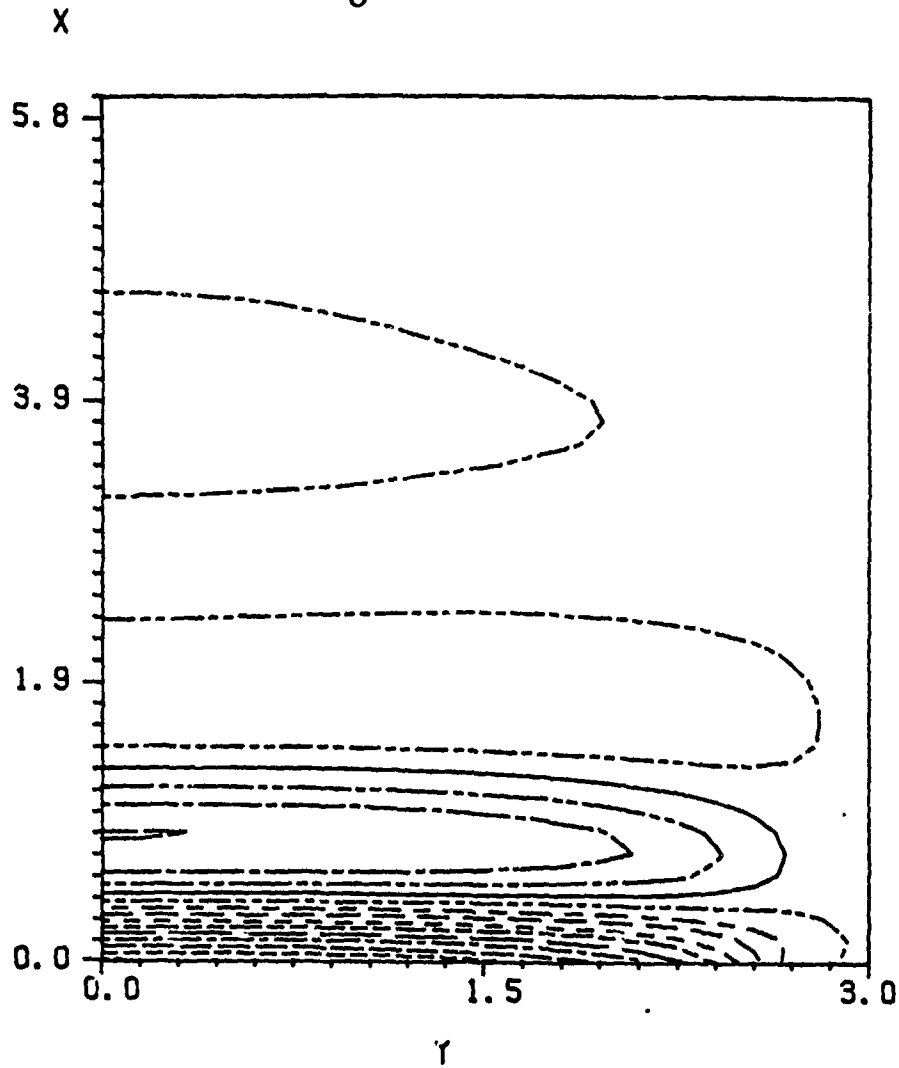
-----	1.5	-----	17.9
-----	34.3	-----	50.7
-----	67.1	-----	83.5
-----	99.9	-----	116.3
-----	132.7	-----	149.1
-----	165.5	-----	181.9
-----	198.3	-----	214.7

ADVANCED SILICON SHEET

The Normal Stress YY Contour Plot
for Modified EFG Profile

Unit of X and Y = CM, Z = MPA

$$N_0 = 2 \times 10^{-7} / \text{cm}^2$$



LEGEND: Z

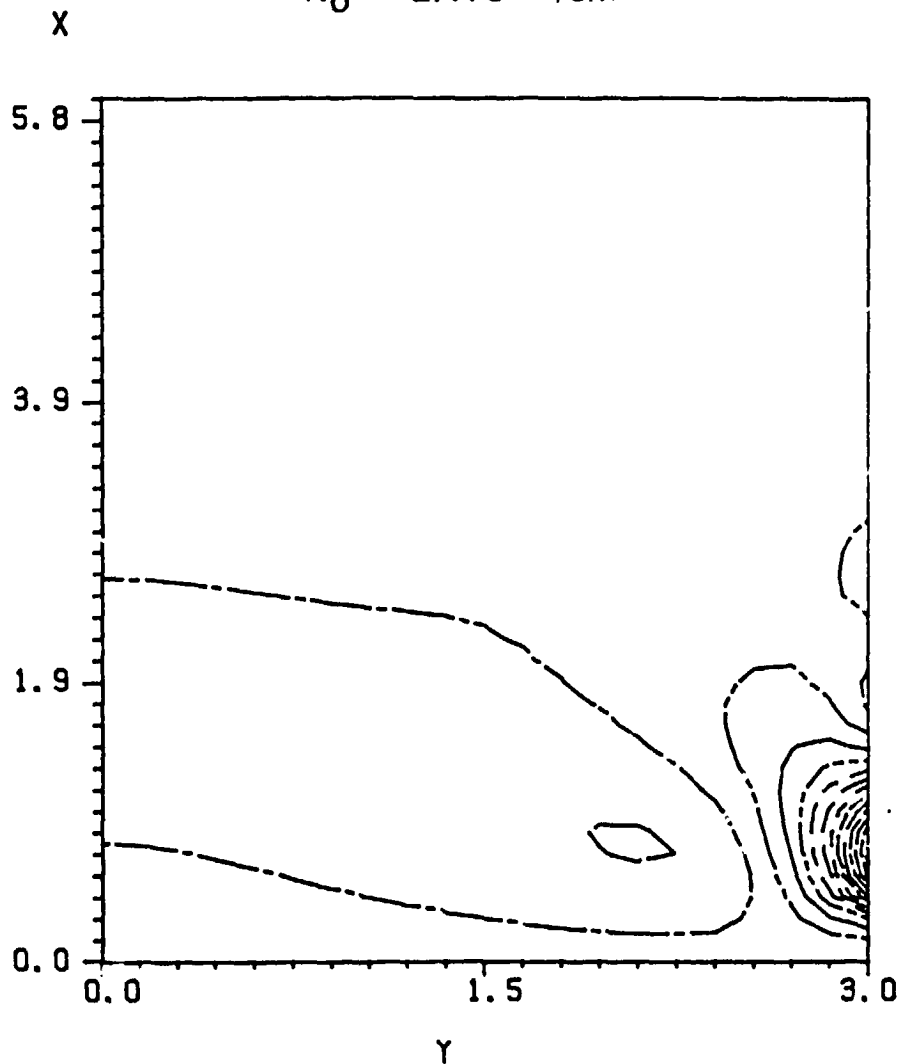
-----	-215.4	-----	-191.8
-----	-168.2	-----	-144.6
-----	-121.0	-----	-97.4
-----	-73.8	-----	-50.2
-----	-26.6	-----	-3.0
-----	20.6	-----	44.2
-----	67.8	-----	91.4

ADVANCED SILICON SHEET

The Normal Stress XX Contour Plot
for Modified EFG Profile

Unit of X and Y = CM, Z = MPA

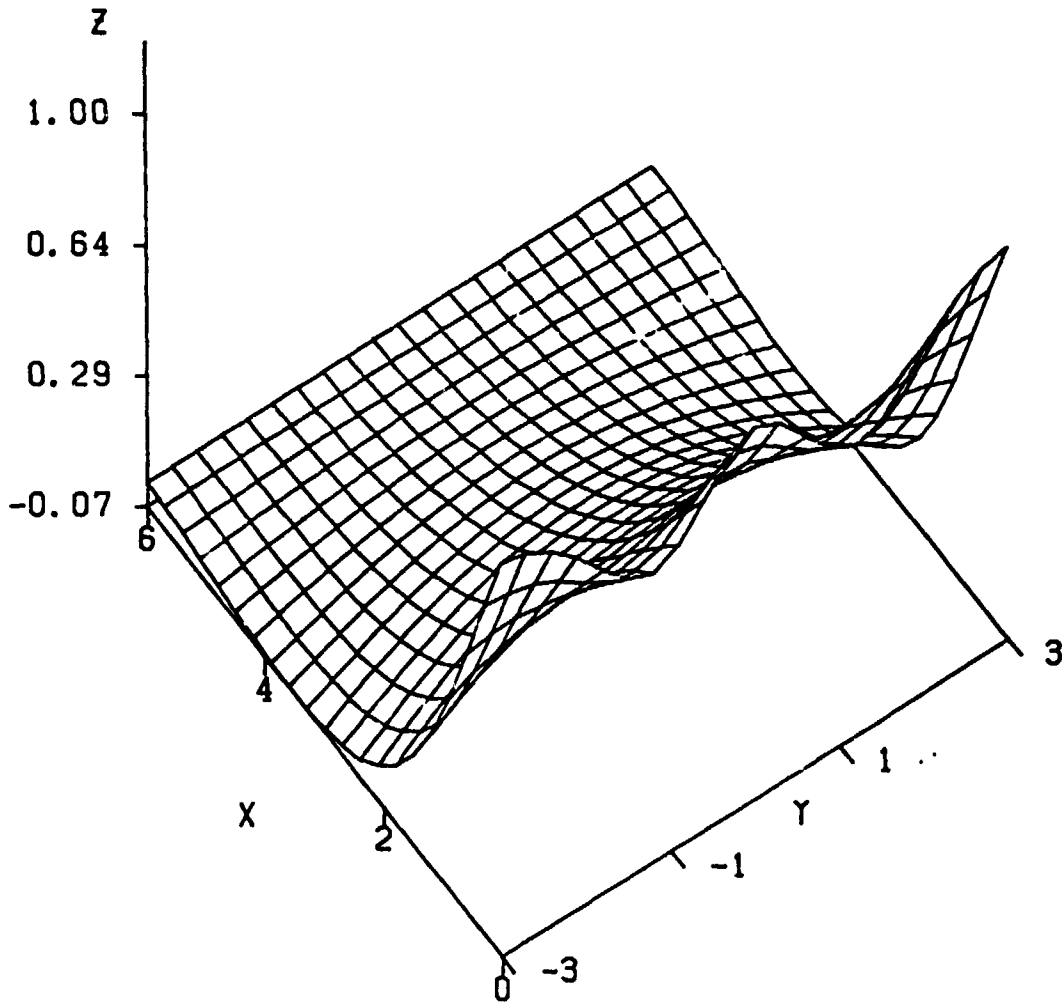
$$N_0 = 2 \times 10^{-7} / \text{cm}^2$$



LEGEND: Z

-----	-150.0	-----	-137.3
-----	-124.6	-----	-111.9
-----	-99.2	-----	-86.5
-----	-73.8	-----	-61.1
-----	-48.4	-----	-35.7
-----	-23.0	-----	-10.3
-----	2.4	-----	15.1

The 13th Buckling Mode
for Modified EFG Profile
Critical Thickness = 0, 027877 MM
Unit of X and Y = CM



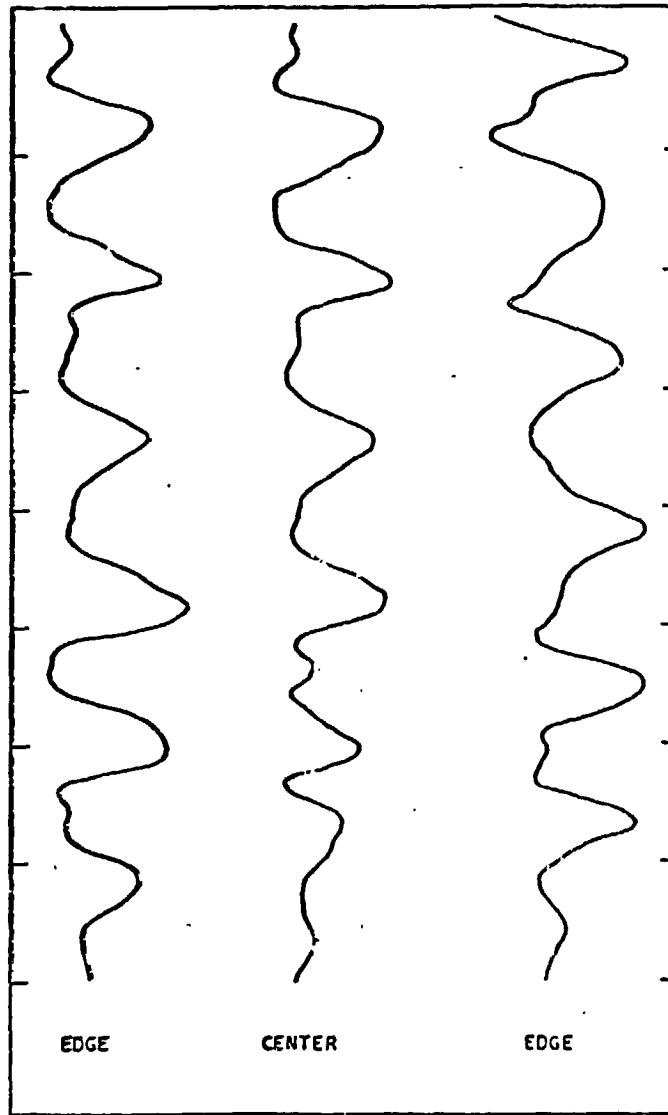


Fig. 1. Surface profile traces illustrating typical edge buckling for ribbon no. 18-102-2 grown at a speed of 3.0 cm/min. Traces are taken along the growth direction, with respect to the width dimension as marked.

MAR 1979

ADVANCED SILICON SHEET

for the case of a 6 cm x 6 cm ribbon pulled at $v_0 = .0005$ m/sec. The results are shown in Table III.

M /cm	N_0 cm/2	N_{f2} /cm ²	N_{tel} / cm ²	$\sigma_{yy_{max}}$ MPa	T_u mm
1.75	.5	Diverge	4.65×10^8	-151.1*	.4698 *
1.0	.3	Diverge	3.175×10^8	-101.7*	
.25	.3	Diverge	$.5941 \times 10^4$	- 17.4*	
.240625	.3	1.06×10^4	$.3137 \times 10^4$	- 17.8	
.2375	.3	1984	$.2527 \times 10^4$	- 16.8	.21364
.225	.3	963	1049	- 15.0	
.200	.3	173	174	- 12.1	.29581

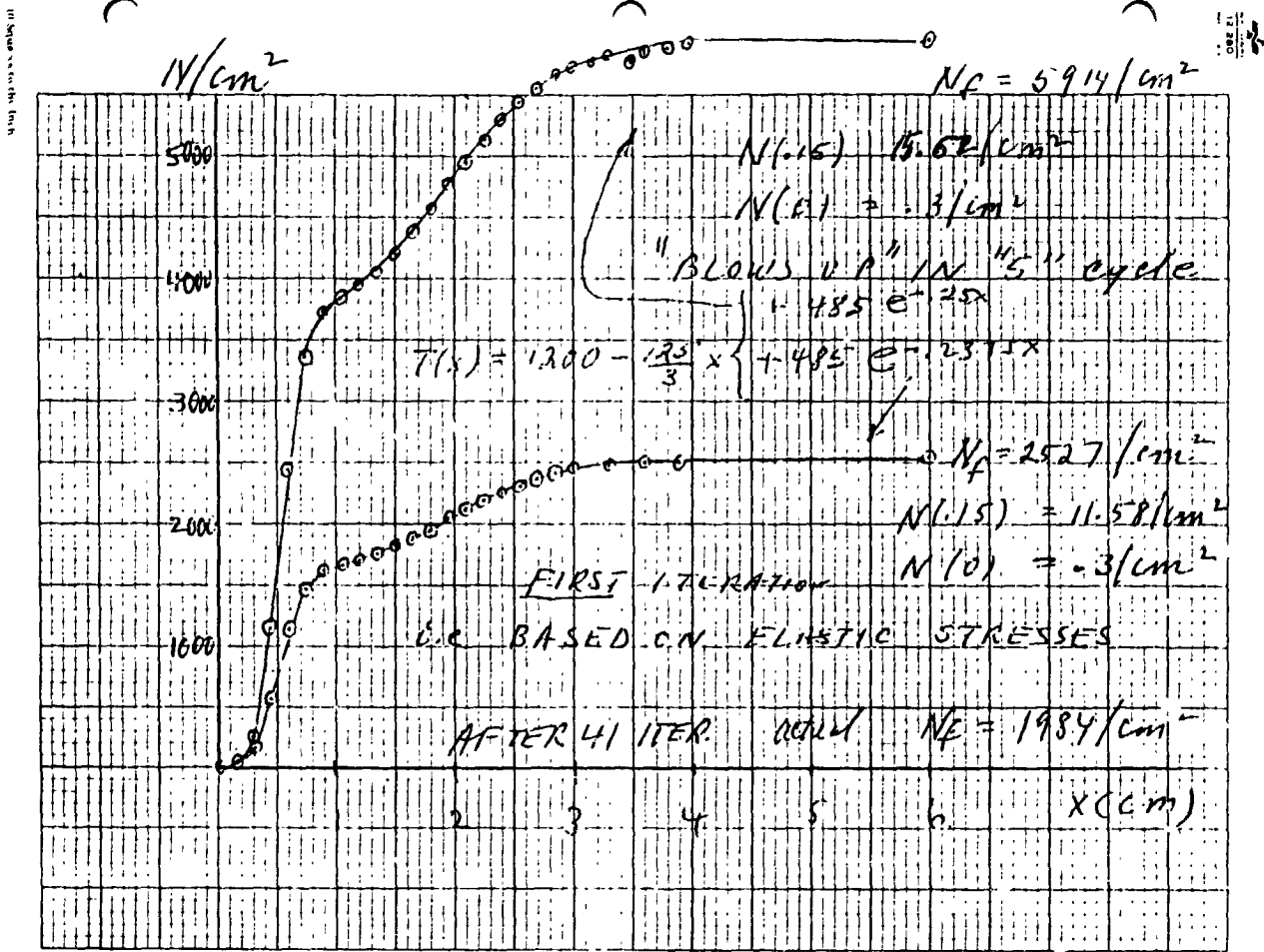
Table III

The * in the last column indicates these are the elastic stresses, because plastic ones are not obtained.

$$T_{NEFG} = 1200 - \frac{125x}{3} + 485e^{-1.75x}$$

This led to divergent solutions under conditions when the Westinghouse profile did not. With this situation in mind we considered the family of thermal profiles, defined by

$$T(x) = 1200 - \frac{125x}{3} + 485 e^{-Mx}$$



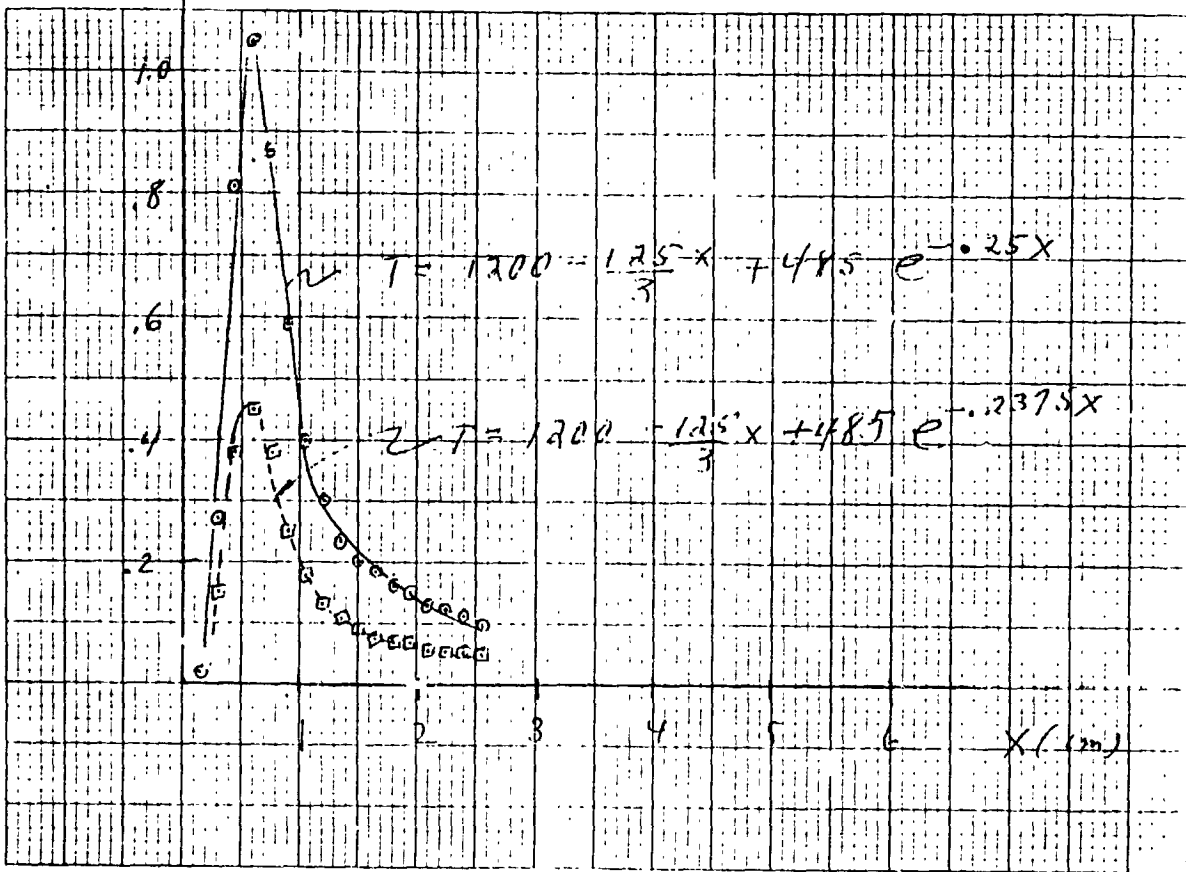
ADVANCED SILICON SHEET

OF POOR QUALITY

$N_0 = 10^{15}/\text{cm}^2$

5
 4
 3
 2
 1
 0

$\frac{P_1}{\Sigma_{XX}} \times 10^5$



ADVANCED SILICON SHEET

Really New Science

Dislocations as part of the stress analysis.
That is $N \neq \text{constant!}$

New

Creep buckling (lowest mode does not dominate!)

Practical

Elastic very useful

Plastic - residual stress

$\tau_{cr} \doteq \tau_{cr} \text{ (elastic)}$

Keep N small

Very sensitive

(ala melting)